



Material Content Data Sheet



Sales Product Name	BTS50060-1EGA			Issued	25. January 2018			
MA#	MA001686936							
Package	PG-DSO-12-16			Weight*	395.26 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.240	0.82	0.82	8197	8197
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		175	
	non noble metal	iron	7439-89-6	0.230	0.06		583	
wire	non noble metal	copper	7440-50-8	230.106	58.21	58.29	582162	582920
	noble metal	gold	7440-57-5	0.194	0.05		491	
encapsulation	non noble metal	aluminium	7429-90-5	1.407	0.36	0.41	3559	4050
	organic material	carbon black	1333-86-4	0.304	0.08		768	
	plastics	epoxy resin	-	21.707	5.49		54919	
leadfinish	inorganic material	silicondioxide	60676-86-0	129.789	32.84	38.41	328362	384049
	non noble metal	tin	7440-31-5	4.235	1.07	1.07	10715	10715
plating	noble metal	silver	7440-22-4	1.852	0.47	0.47	4685	4685
glue	plastics	Polyimide	26023-21-2	0.205	0.05	0.05	518	518
solder	non noble metal	tin	7440-31-5	0.038	0.01		97	
	noble metal	silver	7440-22-4	0.048	0.01		122	
	non noble metal	lead	7439-92-1	1.837	0.46	0.48	4647	4866
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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